Global Compound Semiconductors Corporation emerges

GCS Inc (Global Communications Semiconductor Inc), a US-based, pure-play III-V semiconductor wafer foundry and GCTC (Global Communication Technology Corp), a Taiwan-based pure-play III-V semiconductor wafer foundry, will combine operations and become Global Compound Semiconductors Corporation. The Board of Directors and shareholders of both companies have approved the agreement, which is expected to close in Q1 2004.

"This is a very exciting time in compound semiconductor foundry services and I am reminded of my previous experience in Taiwan during the formation of silicon foundry industry. Like silicon, in the early 90s, we are now seeing growth in III-V foundries fuelled by the expanding telecommunications and wireless markets and the growth of fabless design companies." commented Don Brooks, GCSC's chairman. "The combination of these two companies creates a high-volume, low-cost 6-inch manufacturing facility in Taiwan while maintaining the Torrance facility, known for cutting-edge technologies, meeting the needs for technology-driven, high-performance markets," continued Brooks.

Dr. Sam Lee, currently CEO of GCS, will become CEO of GCSC (See p.43). He said: "The Torrance, California facility is ISO 9001-2000 certified and offers foundry services for InGaP HBT, InP HBT, SAW and PHEMT processes and provides optoelectronic foundry services for QWIP detectors, modulators & PIN diodes used in the surveillance, security and fiber optic communication markets. Several major compound semiconductor device manufacturers, on three continents, have qualified this facility for volume manufacturing programs. GCSC customers will have immediate access to the broadest process portfolio, latest technologies, a worldwide customer service organization, high-volume, low-cost 6-inch manufacturing and one-stop supply chain management."

Merger creates Nissan Taiyo Corporation

Japan's Nippon Sanso Corporation (NSC), parent company of Matheson Tri-Gas Inc (MT), and Taiyo Toyo Sanso (TTS) are to merge on an equal footing, subject to approval by the shareholders of both companies and the relevant public authorities.

Planned for October 1 2004, the merger will form Nissan Taiyo Corporation. TTS' current chairman, Mr. Konosuke Ose, will become chairman of the new Company, and Hiroshi Taguchi, current president and CEO of NSC, will take on the role of president.

Mr. Taguchi said: "Nippon Sanso has tremendous synergies with Taiyo Toyo, from both a technology and market standpoint, and this can be seen as an ideal merger. We will strengthen our company through this merger and generate the cash flow to make capital and R&D investments in our core business areas, such as electronics and gas plants. The top managers of both Companies agree that this merger is the most efficient and effective course of action to accurately respond to the needs of our users."

President and CEO of Matheson Tri-Gas Inc, William Kroll said: "This is a very important event for Matheson Tri-Gas Inc. This merger will create a new entity that will help us compete much more effectively on the global stage. Matheson Tri-Gas Inc is Nippon Sanso's largest subsidiary and we will play a significant role in the consolidated management of this new Company, contributing a strong brand name, technology and products. We will have new opportunities to expand our product portfolio, as well as become a significant supplier of products to the new Nissan Taiyo Corporation."

Veeco sees bright start to 2004

Veeco Instruments Inc has received orders for two GEN2000 MBE systems from an undisclosed manufacturer of RFICs. The multi-wafer 7x6-inch MBE systems will be used in the production of GaAs-based semiconductor devices for wireless communications applications, most notably power amplifiers and integrated circuits used in wireless handsets and WLANs.

"The Semiconductor Industry Association predicts strong growth for RFICs over the next three years, fuelled by mobile handsets and WLAN applications," said Marlin Braun, VP and GM of Veeco MBE Operations. "The addition of non-silicon materials for wireless communications within the 2003 International Technology Roadmap for Semiconductors (ITRS) further supports a positive outlook for compound semiconductor devices."

Veeco's GEN2000 MBE system